

WHAT IS CLAIMED IS:

1. A method of manufacturing a thin film element, comprising:
transferring element chips including at least one of a plurality of functional elements formed on a first substrate onto a second flexible substrate, the element chips being rectangular; and
arranging short sides of the element chips along a curving direction of the second substrate.
2. The method of manufacturing a thin film element according to Claim 1, the functional elements being thin film transistors.
3. A thin film transistor circuit substrate, comprising:
thin film transistors manufactured by the method of manufacturing a thin film element according to Claim 2.
4. An active matrix display device, comprising:
thin film transistors manufactured by the method of manufacturing a thin film element according to Claim 2, the thin film transistors being usable as active matrix elements.
5. An electro-optical device, comprising:
the thin film transistor circuit substrate according to Claim 3.
6. An electronic apparatus, comprising:
the electro-optical device according to Claim 5.